

1. General description

Enhanced ultrafast power diode in a SOT404 (D2PAK) plastic package

2. Features and benefits

- High thermal cycling performance
- Low on-state losses
- Low thermal resistance
- Soft recovery characteristic
- Surface-mountable package

3. Applications

- Dual Mode (DCM and CCM) PFC
- Power Factor Correction (PFC) for Interleaved Topology

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_R	reverse voltage	DC	-	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_{mb} \leq 126$ °C; SQW; Fig. 1 ; Fig. 2	-	-	5	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25$ μ s; $T_{mb} \leq 126$ °C; SQW	-	-	10	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; SIN; Fig. 3	-	-	60	A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; SIN; Fig. 3	-	-	66	A
Static characteristics						
V_F	forward voltage	$I_F = 5$ A; $T_j = 25$ °C; Fig. 5	-	1.3	1.9	V
		$I_F = 5$ A; $T_j = 150$ °C; Fig. 5	-	1.1	1.7	V
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1$ A; $V_R = 30$ V; $di_F/dt = 100$ A/ μ s; $T_j = 25$ °C; Fig. 6	-	17.5	35	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		
2	K	cathode		
3	A	anode		
mb	K	mounting base; connected to cathode		

[1] it is not possible to make connection to Pin 2 of the TO263 package.

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYV25FB-600	TO263	BYV25FB-600,118	Reel	800	TO263N (N)	26-Sep-2016
					TO263P (P)	12-Jun-2023

7. Marking

Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: N	Assembly factory: P
BYV25FB-600	BYV25FB 600 PjNxxxx xx	BYV25FB 600 PjPxxxx xx

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{RRM}	repetitive peak reverse voltage		-	600	V
V _{RWM}	crest working reverse voltage		-	600	V
V _R	reverse voltage	DC	-	600	V
I _{F(AV)}	average forward current	$\delta = 0.5$; T _{mb} ≤ 126 °C; SQW; Fig. 1; Fig. 2	-	5	A
I _{FRM}	repetitive peak forward current	$\delta = 0.5$; t _p = 25 μs; T _{mb} ≤ 126 °C; SQW	-	10	A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; SIN; Fig. 3	-	60	A
		t _p = 8.3 ms; T _{j(init)} = 25 °C; SIN; Fig. 3	-	66	A
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-	150	°C

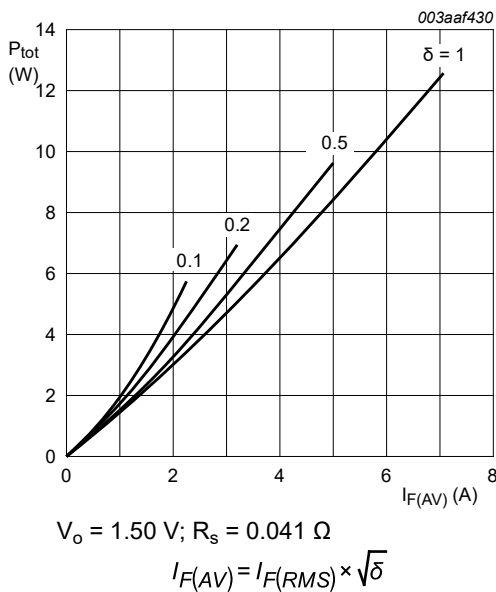


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

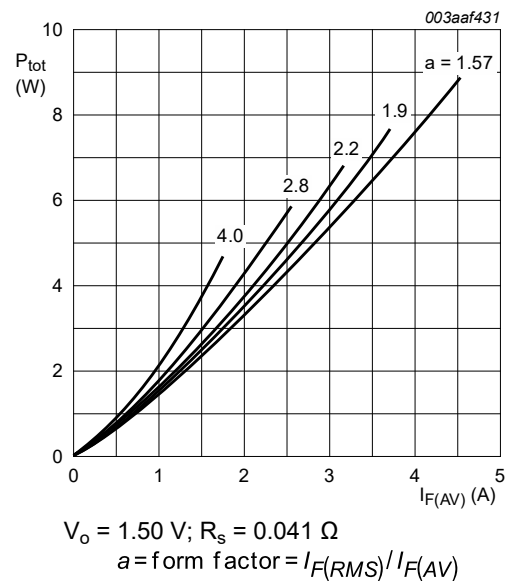


Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

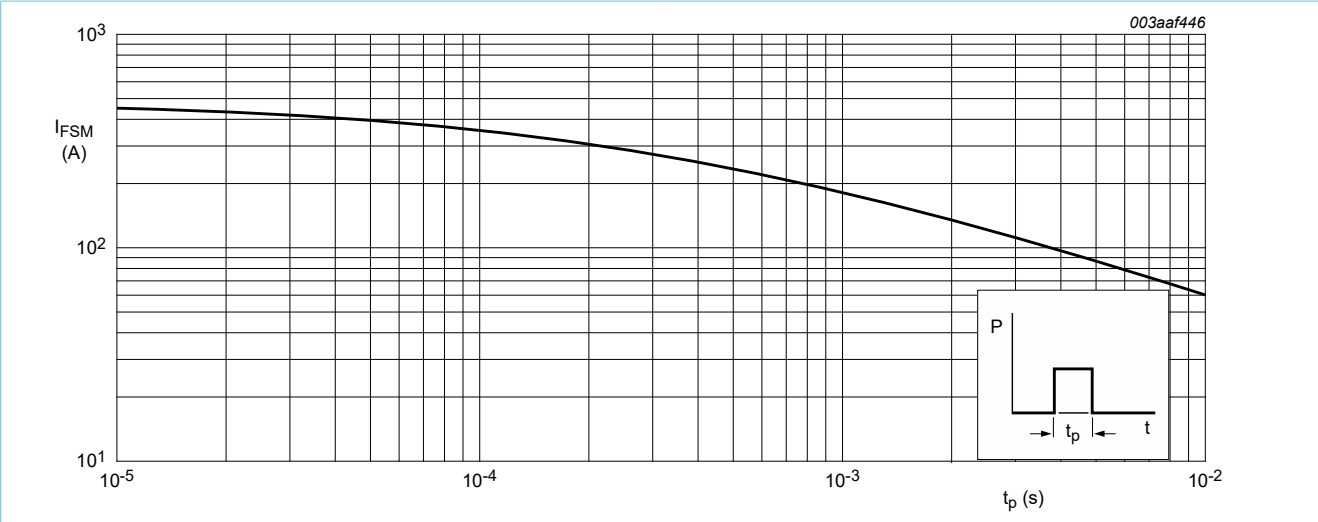


Fig. 3. Non-repetitive peak forward current as a function of pulse width; square waveform; maximum values

9. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4	-	-	2.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	[1]	50	-	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

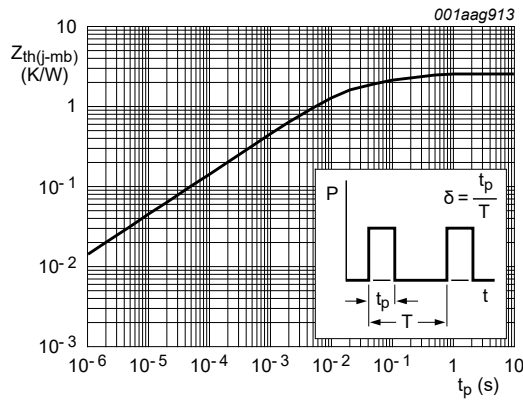


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse width

10. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward voltage	$I_F = 5 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 5}$	-	1.3	1.9	V
		$I_F = 5 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{ Fig. 5}$	-	1.1	1.7	V
I_R	reverse current	$V_R = 600 \text{ V}; T_j = 100 \text{ }^\circ\text{C}$	-	-	1.5	mA
		$V_R = 600 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	50	μA
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 6}$	-	17.5	35	ns
I_{RM}	peak reverse recovery current	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}$	-	1.5	-	A
Q_r	recovered charge		-	13	-	nC
V_{FR}	forward recovery voltage	$I_F = 1 \text{ A}; dI_F/dt = 100 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$	-	3.2	-	V

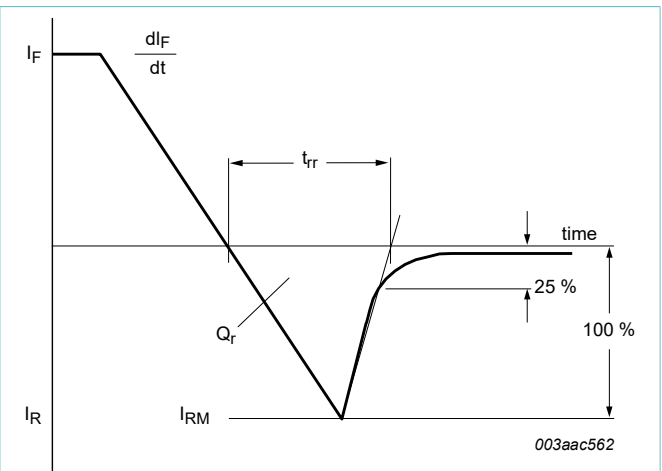
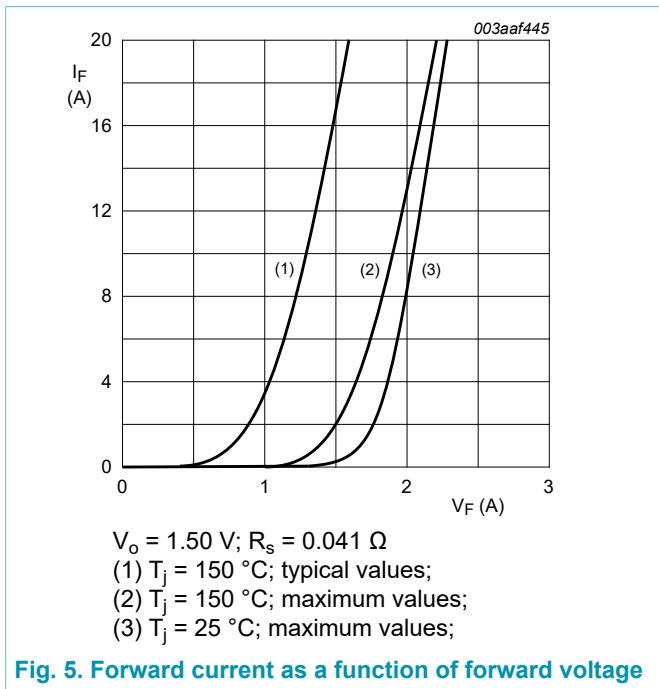


Fig. 6. Reverse recovery definitions; ramp recovery

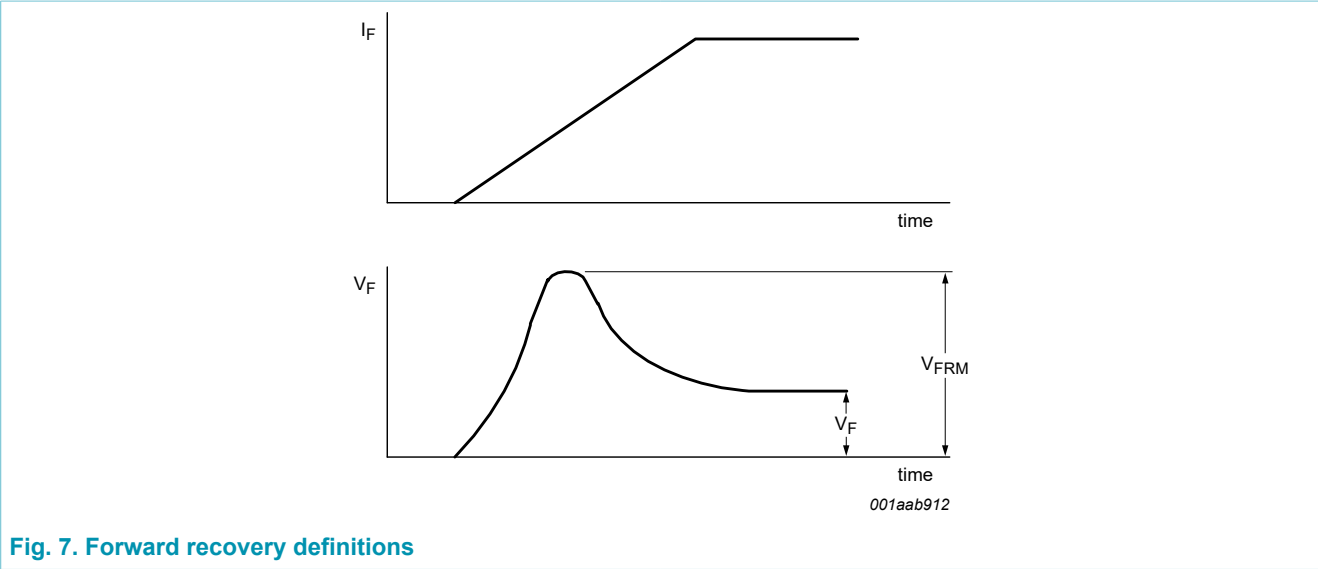
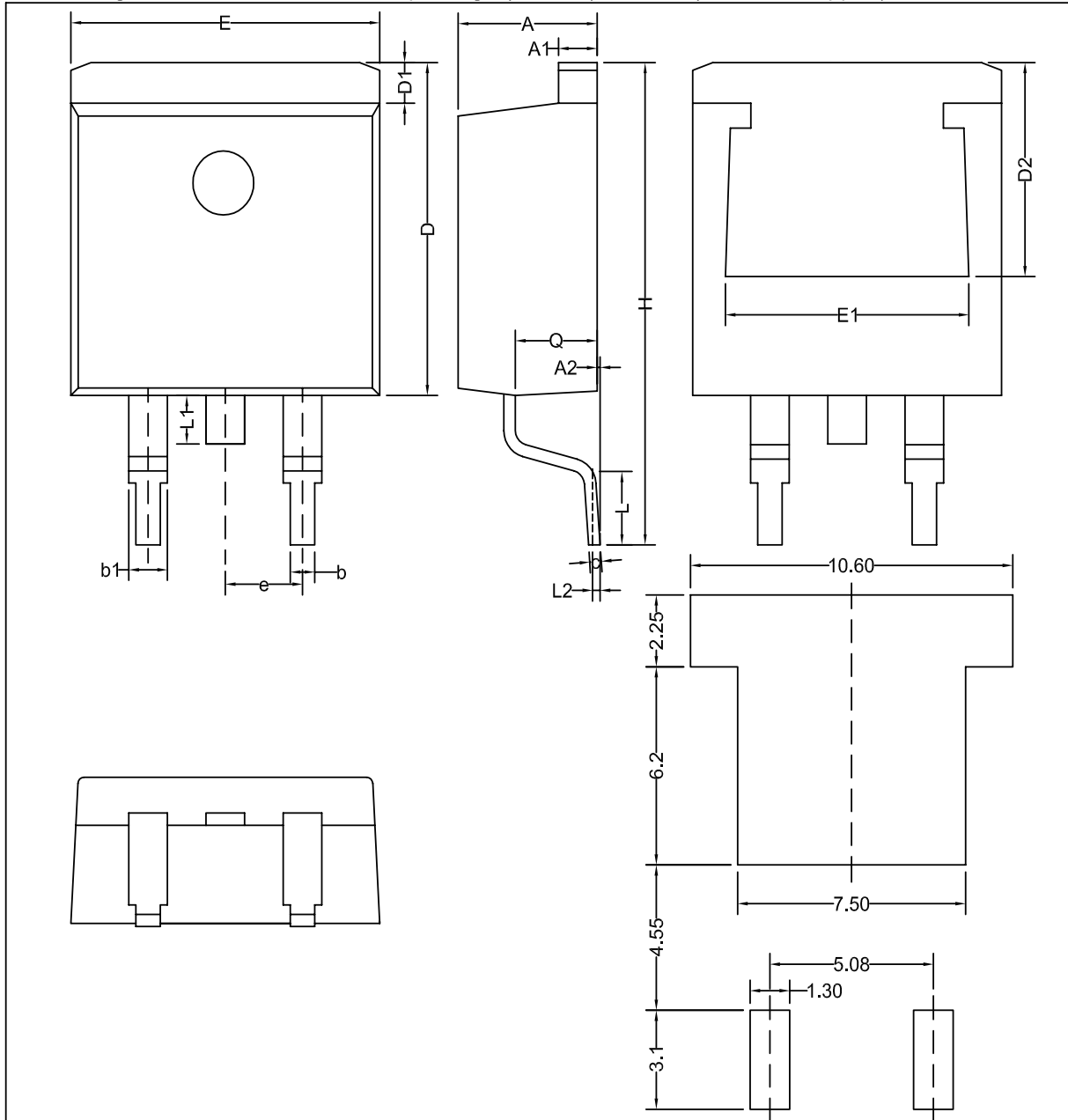


Fig. 7. Forward recovery definitions

11. Package outline

Assembly factory: N

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) TO263



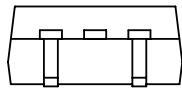
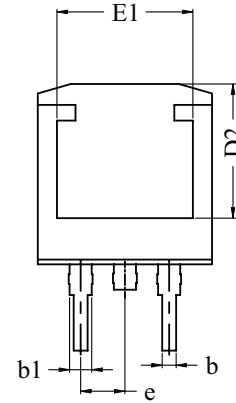
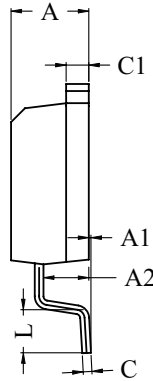
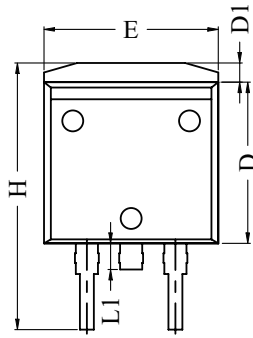
Recommended Footprint

Unit	A	A1	A2	b	b1	c	D	D1	D2	e	E	E1	H	L	L1	L2	Q
min	4.10	1.22	0.00	0.60	1.05	0.34	---	1.20	6.60	2.54 (BSC)	9.70	7.80	14.80	2.10	---	0.25 (BSC)	2.20
max	4.70	1.40	0.25	0.90	1.45	0.64	11.00	1.60	---	---	10.30	---	15.80	2.90	1.75	---	2.79

Assembly factory: P

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

TO263



Dim	All Dimensions in Millimeters		
	Min	Typ	Max
A	4.30	4.46	4.60
A1	0	0.13	0.25
A2	2.50	2.60	2.70
b	0.70	0.80	0.90
b1	1.10	1.27	1.45
C	0.40	0.52	0.60
C1	1.17	1.30	1.40
D	9.10	9.25	9.40
D1	1.00	1.10	1.30
D2	7.40	7.70	8.00
E	9.80	10.00	10.20
E1	7.60	7.80	8.00
e	2.54 BSC		
H	14.80	15.30	15.80
L	2.10	2.47	2.80
L1	1.30	1.50	1.70

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Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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